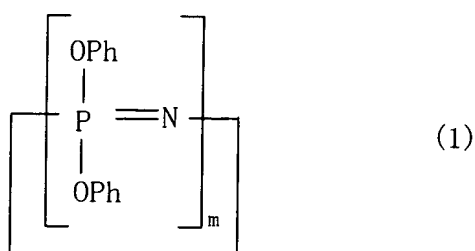
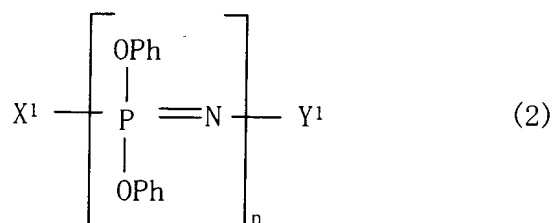


WHAT IS CLAIMED IS:

1. A heat-resistant composition containing solvent-soluble polyimide resin (A) and a phosphazene compound (B), wherein said phosphazene compound (B) includes at least either a cyclic phenoxyphosphazene compound (B1) expressed in the following chemical formula (1):

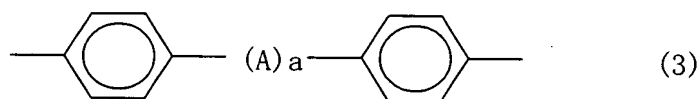


where m represents an integer of 3 to 25 and Ph represents a phenyl group, or a chain phenoxyphosphazene compound (B2) expressed in the following chemical formula (2):



where X^1 represents group $-\text{N} = \text{P}(\text{OPh})_3$ or group $-\text{N} = \text{P}(\text{O})\text{OPh}$, Y^1 represents group $-\text{P}(\text{OPh})_4$ or group $-\text{P}(\text{O})(\text{OPh})_2$, n represents an integer of 3 to 10,000 and Ph represents a phenyl group,

or a cross-linked phenoxyphosphazene compound (B3) cross-linked by a cross-linking group including at least one of an o-phenylene group, an m-phenylene group, a p-phenylene group and a bisphenylene group expressed in the following chemical formula (3):



where A represents $-\text{C}(\text{CH}_3)_2-$, $-\text{SO}_2-$, $-\text{S}-$ or $-\text{O}-$ and a represents 0 or 1, with respect to said phosphazene compound including at least either said cyclic phenoxyphosphazene compound (B1) or said chain phenoxyphosphazene compound (B),

so that said cross-linking group intervenes between two oxygen atoms desorbed by said phenyl group of said phosphazene compound and the phenyl group content is 50 to 99.9 % with reference to the total number of phenyl groups contained in said phosphazene compound including at least said cyclic phenoxyphosphazene compound (B1) or said chain phenoxyphosphazene compound (B2) with no free hydroxyl groups in molecules.

2. The heat-resistant composition according to claim 1, wherein said polyimide resin (A) is polyimide resin, containing a solvent solubility imparting component selected from at least one of an aliphatic compound component, an alicyclic compound component and an alkylene oxide adduct component of a bisphenol compound, soluble in a solvent containing a low-boiling solvent.

3. The heat-resistant composition according to claim 1, containing a reactive compound (C) selected from at least one of an epoxy compound, an acrylic compound and an isocyanate compound.

4. The heat-resistant component according to claim 1, wherein said polyimide resin (A) is polyamide imide resin, and said reactive compound (C) is an epoxy compound.

5. The heat-resistant composition according to claim 1, wherein said polyimide resin (A) is polyester imide resin, and said reactive compound (C) is an epoxy compound.

6. The heat-resistant composition according to claim 1, wherein said polyimide resin (A) is polyether imide resin, and said reactive compound (C) is an epoxy compound.

7. An adhesive for a printed wiring board employing the heat-resistant composition according to claim 1.

8. An adhesive sheet for a printed wiring board employing the heat-resistant composition according to claim 1.

9. A multilayer printed wiring board employing the heat-resistant composition according to claim 1.

10. A sealant for a printed wiring board employing the heat-resistant composition according to claim 1.

11. An insulating circuit protective film for a printed wiring board employing the heat-resistant composition according to claim 1.

12. A circuit protective agent employing the heat-resistant composition according to claim 1.

13. A cover-lay film employing the heat-resistant composition according to claim 1.

14. A cover ink employing the heat-resistant composition according to claim 1.

15. A substrate for a printed wiring board employing the heat-resistant composition according to claim 1.

16. A metal-clad laminate employing the heat-resistant composition according to claim 1.

17. A conductive paste for a printed wiring board employing the heat-resistant composition according to claim 1.

10071624-020802